

Single Phase Glass Passivated Silicon Bridge Rectifier

$V_{RRM} = 50\text{ V} - 400\text{ V}$

$I_O = 8\text{ A}$

Features

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- High case dielectric strength of 1500 V_{RMS}
- Glass passivated chip junction
- Ideal for printed circuit boards
- High surge overload rating
- High temperature soldering guaranteed: 260°C/ 10 seconds, 0.375 (9.5mm) lead length
- Not ESD Sensitive

Mechanical Data

Case: Molded plastic body over passivated junctions

Terminals: Plated leads, solderable per MIL-STD-750 Method 2026.

Mounting position: Any

Maximum ratings at $T_c = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	GBU8A	GBU8B	GBU8D	GBU8G	Unit
Repetitive peak reverse voltage	V_{RRM}		50	100	200	400	V
RMS reverse voltage	V_{RMS}		35	70	140	280	V
DC blocking voltage	V_{DC}		50	100	200	400	V
Operating temperature	T_j		-55 to 150	-55 to 150	-55 to 150	-55 to 150	$^\circ\text{C}$
Storage temperature	T_{stg}		-55 to 150	-55 to 150	-55 to 150	-55 to 150	$^\circ\text{C}$

Electrical characteristics at $T_c = 25\text{ }^\circ\text{C}$, unless otherwise specified

Single phase, half sine wave, 60 Hz, resistive or inductive load

For capacitive load derate current by 20%

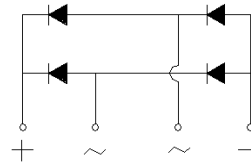
Parameter	Symbol	Conditions	GBU8A	GBU8B	GBU8D	GBU8G	Unit
Maximum average forward rectified current ^{1,2}	I_O	$T_c = 100\text{ }^\circ\text{C}$	8.0	8.0	8.0	8.0	A
Peak forward surge current	I_{FSM}	$t_p = 8.3\text{ ms}$, half sine	200	200	200	200	A
Maximum instantaneous forward voltage drop per leg	V_F	$I_F = 8\text{ A}$	1.1	1.1	1.1	1.1	V
Maximum DC reverse current at rated DC blocking voltage per leg	I_R	$T_a = 25\text{ }^\circ\text{C}$ $T_a = 125\text{ }^\circ\text{C}$	5 500	5 500	5 500	5 500	μA
Rating for fusing	I^2t	$t < 8.3\text{ ms}$	166	166	166	166	A^2sec
Typical junction capacitance per leg ³	C_j		211	211	211	211	pF
Typical thermal resistance per leg ^{1,2}	$R_{\theta JA}$ $R_{\theta JL}$		21 2.2	21 2.2	21 2.2	21 2.2	$^\circ\text{C/W}$

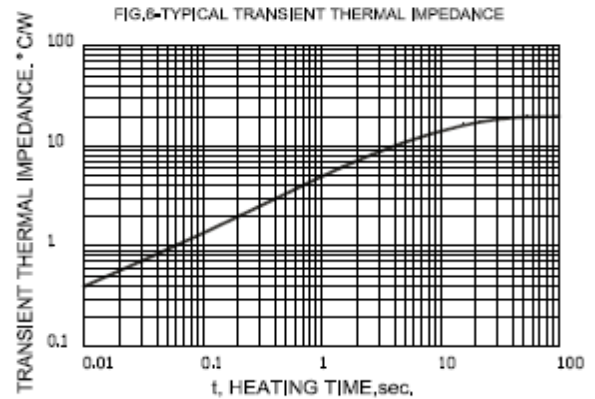
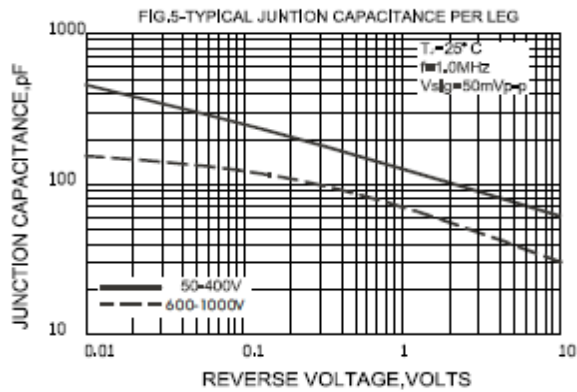
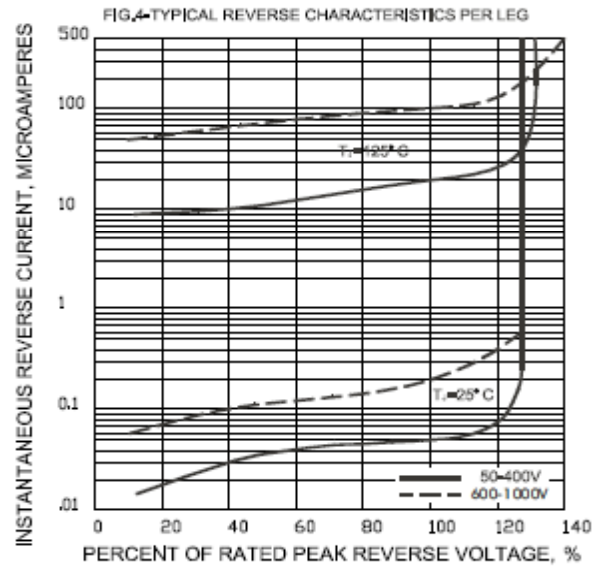
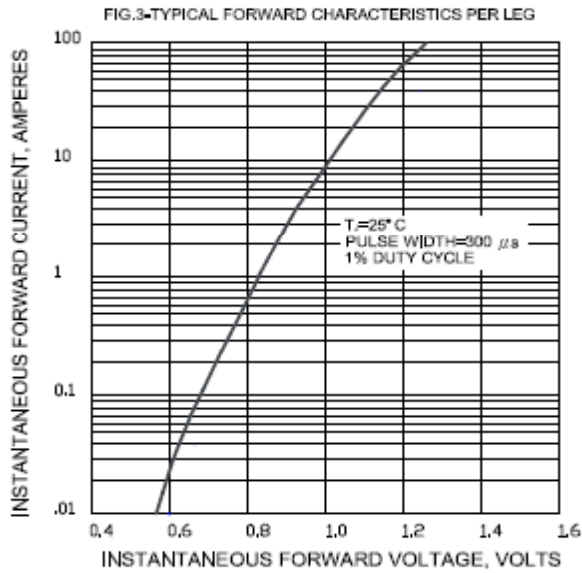
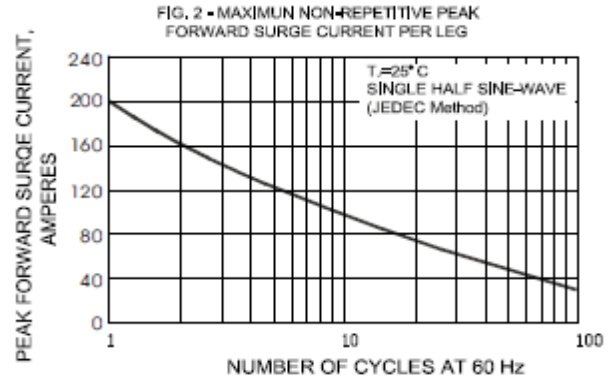
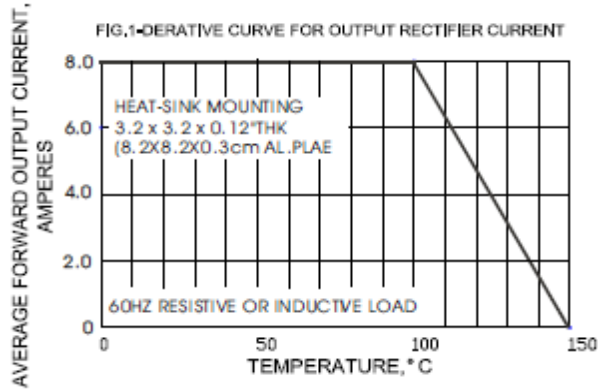
¹ - Device mounted on 82 mm x 82 mm x 3 mm Al plate heatsink

² - Recommended mounted position is to bolt down device on a heatsink with silicon thermal compound for maximum heat transfer using #6 screw.

³ - Measured at 1.0 MHz and applied reverse bias of 4.0 V

GBU Package

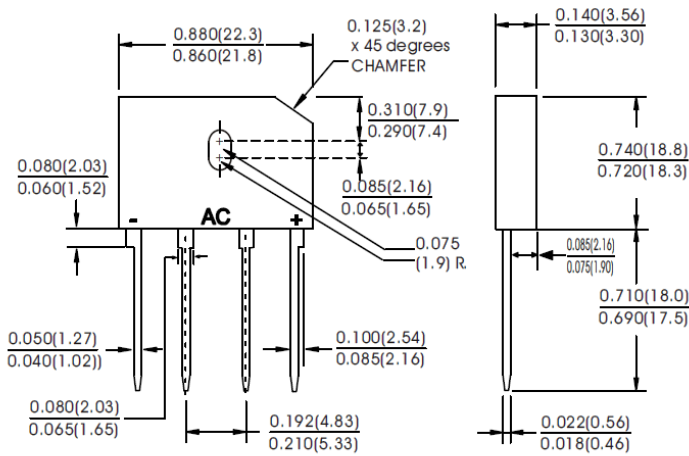




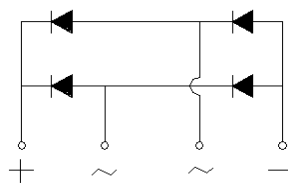
Package dimensions and terminal configuration

Product is marked with part number and terminal configuration.

GBU



Dimensions in inches and (millimeters)



Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[GeneSiC Semiconductor:](#)

[GBU8A](#) [GBU8B](#) [GBU8D](#) [GBU8G](#)